

Application No. 10/646,696  
Amendment dated October 26, 2006  
Reply to Office Action of July 26, 2006

Docket No.: 4444-0124P

**AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) An Internet automatic electrical data system, comprising:
  - a process controller, ~~used~~ configured to process an analyzing order for integrated circuit (IC) packages entrusted by clients;
  - a working database coupled to said process controller, and used to store the IC package parameters inputted by said clients;
  - a condition parameter database coupled to said process controller to provide the condition parameters relative to the ~~a~~ model of the IC package entrusted by said clients;
  - an electrical simulation and analyzing software used to analyze said IC package parameters inputted by said clients, and said condition parameters provided by said condition parameter database;
  - a report form generator coupled to said electrical simulation and analyzing software to generate a report form of analyzed results; and
  - replying means coupled to said report form generator to send said report forms ~~form~~ to said clients.
2. (Previously Presented) The system of claim 1, wherein said clients transmit said IC package parameters through the Internet.
3. (Previously Presented) The system of claim 1, wherein said replying means sends said report forms to said clients utilizing at least one of electronic mail and facsimile.

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4. (Previously Presented) The system of claim 1, wherein said process controller accesses said condition parameters from said condition parameter database, and then transfers said condition parameters along with said IC package parameters inputted by said clients to said electrical simulation and analyzing software.

5. (Previously Presented) The system of claim 1, wherein the IC package types provided by said condition parameter database comprise BGA (ball grid array), BCC, QFP, SOP, QFN (quad flat no-lead), Flip Chip, CSP (chip scale package), and WLCSP (wafer level chip scale package).

6. (Previously Presented) The system of claim 1, wherein said IC package parameters inputted by said clients comprise the number of I/O (input and output) terminals, package type, substrate layer, substrate thickness, information about lead frame, and frequency.

7. (Previously Presented) The system of claim 1, wherein said electrical simulation and analyzing software constructs a three-dimensional model according to said IC package parameters and said condition parameters.

8. (Previously Presented) The system of claim 7, wherein said electrical simulation and analyzing software calculates the resistance, inductance and capacitance of said IC package according to said IC package parameters and said condition parameters.

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9. (Currently Amended) The system of claim 1, wherein said electrical simulation and analyzing software transfers said analyzing result-analyzed results to said report form generator.

10. (Previously Presented) A method for automatically analyzing electrical data through the Internet, comprising the following steps:

inputting IC package parameters for analyzing by a client;

transferring said IC package parameters to a working database for storing through the Internet;

accessing said IC package parameters from said working database and condition parameters relative to said IC package parameters from a condition parameter database by a process controller;

transferring said IC package parameters and said condition parameters to an electrical simulation and analyzing software for simulating and analyzing by said process controller to generate an analyzed result;

transferring the analyzed result to a report form generator for generating a report form of analyzed result;

transferring said report form via said report form generator to a replying means; and sending said report form to said client by said replying means.

11. (Previously Presented) The method of claim 10, wherein said client transmits said IC package parameters through the Internet.

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12. (Cancelled)

13. (Previously Presented) The method of claim 10, wherein said IC package parameters inputted by said client comprises the number of I/O terminals, package type, the number of the substrate layer, substrate thickness, information about lead frame, and frequency.

14. (Previously Presented) The method of claim 10, wherein said electrical simulation and analyzing software constructs a three-dimensional model according to said IC package parameters and said condition parameters.

15. (Previously Presented) The method of claim 14, wherein said electrical simulation and analyzing software calculates the resistance, inductance, and capacitance of said IC package according to said IC package parameters and said condition parameters.

16. (Previously Presented) The method of claim 10, wherein the IC package types provided by said condition parameter database comprise BGA (ball grid array), BCC, QFP, SOP, QFN (quad flat no-lead), Flip Chip, CSP (chip scale package), and WLCSP (wafer level chip scale package).